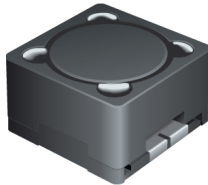


MATERIAL DECLARATION SHEET



Material Number	SRR1208 Series			
Product Line	Shielded SMD Power Inductor			
Compliance Date	2026/04/28			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Core	Ferrite	2.7	Iron oxide (Fe2O3)	1309-37-1	52.0	33.034	63.53
				Zinc oxide (ZnO)	1314-13-2	15.0	9.529	
				Cupric oxide(CuO)	1317-38-0	17.0	10.800	
				Nickel oxide (NiO)	1313-99-1	16.0	10.165	
2	WIRE	Copper	0.9	Copper(Cu)	7440-50-8	95.0	20.118	21.18
				Modified Polyester Resin	-	5.0	1.059	
3	Base	LCP	0.32	Aromatic polyester resin	60088-52-0	65.0	4.894	7.53
				Glass fiber	65997-17-3	34.0	2.560	
				Carbon black	1333-86-4	1.0	0.075	
		Copper	0.12	Copper (Cu)	7440-50-8	66.3	1.872	2.82
				Zinc(Zn)	7440-66-6	33.7	0.952	
		Plating	0.010	Tin (Sn)	7440-31-5	75.0	0.176	0.24
Nickel (Ni)	7440-02-0			25.0	0.059			
4	Adhesive	Resin	0.03	Bisphenol A Epoxy Resin	25068-38-6	60.0	0.424	0.71
				Dicyandiamide	461-58-5	6.5	0.046	
				Poly urethane	51852-81-4	6.5	0.046	
				Carbon black	1333-86-4	2.5	0.018	
				Silicon dioxide	14808-60-7	24.5	0.173	

MATERIAL DECLARATION SHEET



5	Adhesive	Resin	0.14	Bisphenol A Epoxy Resin	25068-38-6	66.0	2.174	3.29
				Dicyandiamide	461-58-5	6.0	0.198	
				Carbon black	1333-86-4	5.0	0.165	
				Aluminum hydroxide	21645-51-2	23.0	0.758	
6	Solder bar	Tin	0.01	Tin (Sn)	7440-31-5	100.0	0.235	0.24
7	Solder wire	Tin	0.01	Tin (Sn)	7440-31-5	97.0	0.228	0.24
				Copper (Cu)	7440-50-8	3.0	0.007	
8	Tape	Tape	0.01	1,3-Benzenedicarbonyl dichloride	25765-47-3	94.0	0.221	0.24
				Ammonium polyphosphate	68333-79-9	1.5	0.004	
				Acrylic	25085-41-0	4.5	0.011	
			Total weight			4.25		

This Document was updated on: 2026/04/28